

# SOT542-1

plastic thin fine-pitch ball grid array package; 56 balls; body  
6 x 6 x 0.8 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	TFBGA56
<b>Package type industry code</b>	TFBGA56
<b>Package style descriptive code</b>	TFBGA (thin fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-195
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	10-6-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.9	-	6	6.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	[tbd]	-	1.1	1.1	mm
A <sub>2</sub>	package height	0.75	-	0.8	0.85	mm
n <sub>2</sub>	actual quantity of termination	-	-	56	-	



2. Package outline

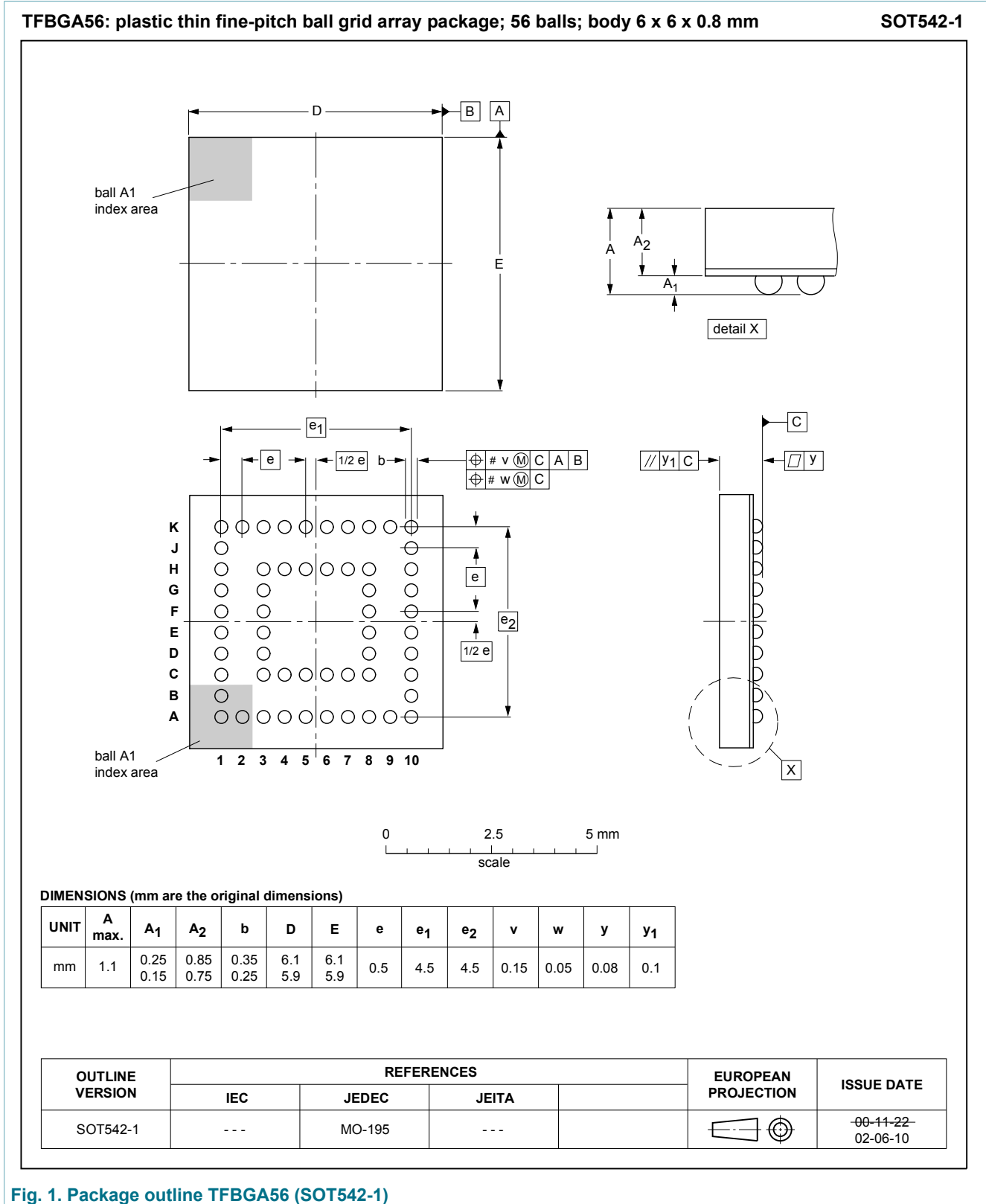
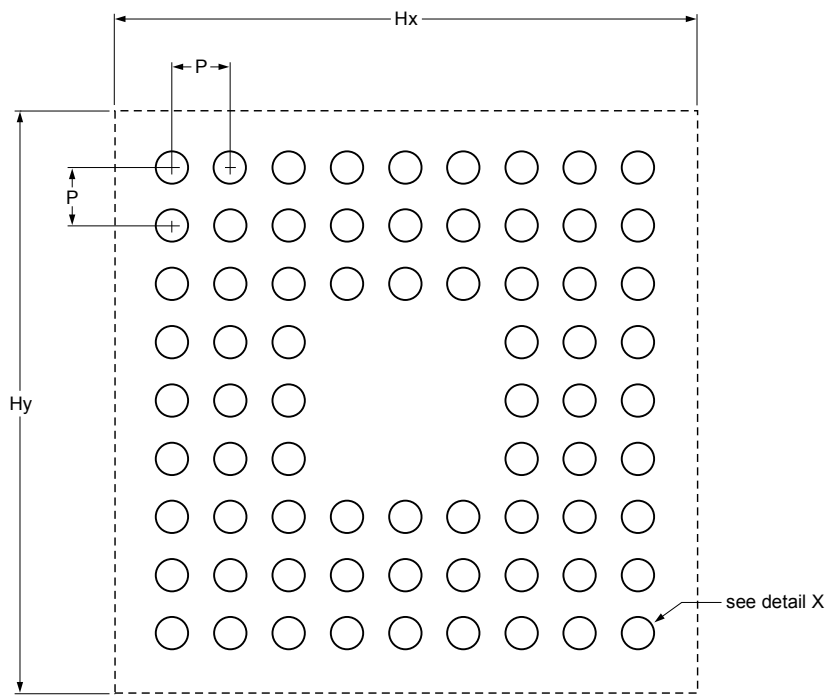


Fig. 1. Package outline TFBGA56 (SOT542-1)




### 3. Soldering

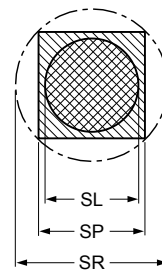
Footprint information for reflow soldering of TFBGA56 package

SOT542-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist



detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.50	0.275	0.300	0.425	6.500	6.500

tot542-1\_fr

Fig. 2. Reflow soldering footprint for TFBGA56 (SOT542-1)

## 4. Legal information

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